

(0.635 mm) .025"

MEC6-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μm (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(4.22 mm) .166" to

(5.66 mm) .223"

Current Rating:

1.7 A per pin

(6 adjacent pins powered)

Voltage Rating:

210 VAC

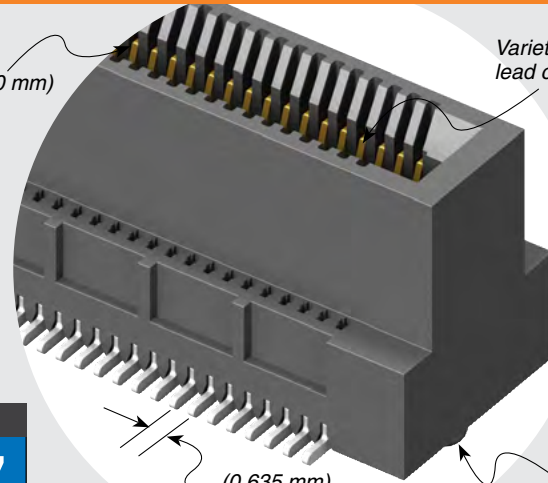
RoHS Compliant:

Yes

Mates with:
(1.60 mm) .062" thick card

Mates with (1.60 mm)
.062" thick card

Variety of
lead counts



Alignment pin

(0.635 mm)
.025" pitch

HIGH-SPEED CHANNEL PERFORMANCE

MEC6-DV

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

17
Gbps

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (10-50)

(0.15 mm) .006" max (60-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
- Other platings
- Contact Samtec.

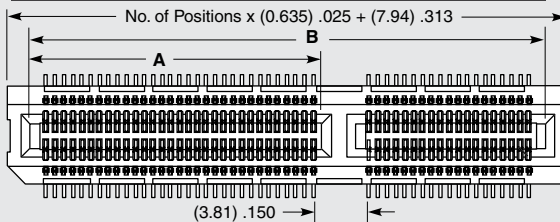
Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable.



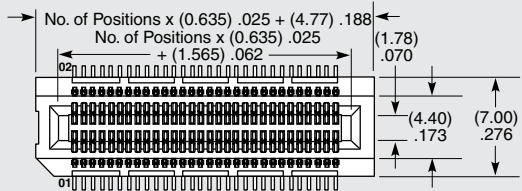
10, 20, 30, 40, 50, 60, 70



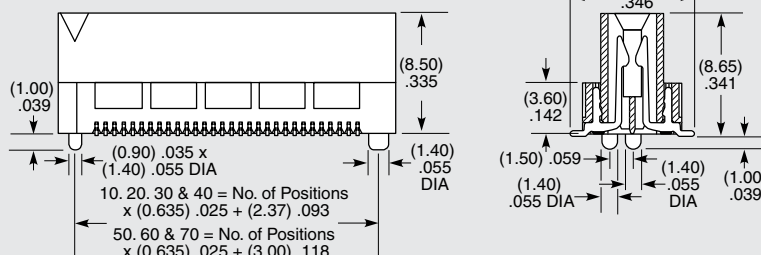
-L
= 10 μm (0.25 μm)
Gold on contact,
Matte Tin on tail

-K
= (5.50 mm) .217" DIA
Polyimide Pick
& Place Pad

-TR
= Tape & Reel



POSITIONS PER ROW	A	B
50	(21.06) .829	(36.49) 1.437
60	(24.87) .979	(42.84) 1.687
70	(28.68) 1.129	(49.19) 1.937



10, 20, 30 & 40 = No. of Positions
x (0.635) .025 + (2.37) .093

50, 60 & 70 = No. of Positions
x (0.635) .025 + (3.00) .118